

## PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT5407861

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SUNG-HOON AHN	02/28/2019
GIL-YONG LEE	02/28/2019
HYUNG-SOO KIM	02/28/2019
MIN-SOO KIM	02/28/2019
HO-JIN KIM	02/28/2019
SOO-HONG MIN	02/28/2019
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SEOUL NATIONAL UNIVERSITY R&DB FOUNDATION
<b>Street Address:</b>	SAN 56-1
<b>City:</b>	SEOUL
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	151-742
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	15915139
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(212)681-0300
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	2126810600
<b>Email:</b>	dflaherty@ocfblaw.com
<b>Correspondent Name:</b>	OSTRAGER CHONG FLAHERTY & BROITMAN P.C.
<b>Address Line 1:</b>	570 LEXINGTON AVENUE
<b>Address Line 2:</b>	19TH FLOOR
<b>Address Line 4:</b>	NEW YORK, NEW YORK 10022
<b>ATTORNEY DOCKET NUMBER:</b>	17-1808
<b>NAME OF SUBMITTER:</b>	DENNIS M. FLAHERTY
<b>SIGNATURE:</b>	/Dennis Flaherty/
<b>DATE SIGNED:</b>	03/06/2019

**Total Attachments: 2**

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## ASSIGNMENT

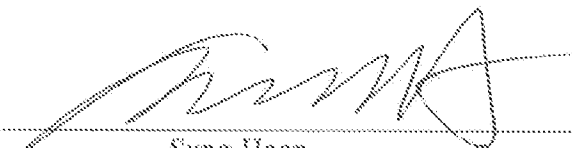
WHEREAS, Sung-Hoon Ahn, residing at 13589, 414-1401, Junganggonwon-ro 20-gil, Bundang-gu, Seongnam-si, Gyeonggi-do, South Korea, Gil-Yong Lee, residing at 05039, 68-3, Gwangnaru-ro 36-gil, Gwanjin-gu, Seoul, South Korea, Hyung-Soo Kim, residing at 08787, 1304 Puravida2, 37, Nambusunhwan-ro 218-gil, Gwanak-gu, Seoul, South Korea, Min-Soo Kim, residing at 08805, Rm. 302, 15, Namhyun 4-gil, Gwanak-gu, Seoul, South Korea, Ho-Jin Kim, residing at 08799, Myville Rm.107, 49-8, Nakseongdaeyeok 8-gil, Gwanak-gu, Seoul, South Korea, and Soo-Hong Min, residing at 07004, 102-1702 Doosan-Weve Apt, 31, Sadang-ro 13-gil, Dongjak-gu, Seoul, South Korea (hereinafter "Assignors"), have invented certain new and useful inventions and improvements (hereinafter "Invention") described in the United States patent application entitled "Three-Dimensional Printing of Composite Repair Patches and Structures", by which the Assignors are making application for LETTERS PATENT OF THE UNITED STATES, which application has been duly executed by Assignors concurrently herewith;

WHEREAS, Seoul National University R&DB Foundation, a corporation organized and existing under the laws of 산업교육진흥 및 산학연협력촉진에 관한 법률, having a place of business at SAN 56-1, SHINRIMODONG KWANAK-KU, SEOUL 151-742, REPUBLIC OF KOREA, with a mailing address of chltngns@snu.ac.kr (hereinafter called "the Assignee"), is desirous of acquiring the entire right, title and interest in and to the Invention within the United States of America and its territorial possessions and all foreign countries, and in and to any United States or foreign LETTERS PATENT that may be granted therefor;

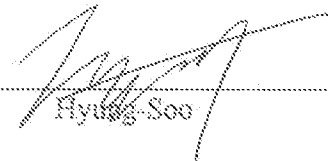
NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, Assignors have assigned, sold and transferred, and do assign, sell and transfer to the Assignee, its successors and assigns, their entire right, title and interest in and to the Invention within the United States of America and its territorial possessions and all foreign countries, and in and to any LETTERS PATENT of the United States and foreign countries, including utility models, inventor's certificates and like government grants that may be granted for any and all portions thereof, and in and to the patent application identified above and applications for patent filed for the Invention in all foreign countries and all provisional, divisional, reissue, continuation, continuation-in-part applications and extensions of any of the applications for patent or LETTERS PATENT identified herein, including all applications claiming the priority of said applications for patent or LETTERS PATENT identified herein, and the right to apply for LETTERS PATENT in foreign countries with full benefit of such priorities as may now or hereafter be granted to Assignors by local laws or by treaty, including any international convention, for the protection of industrial property, together with the right to extend the protection of the United States LETTERS PATENT to the various territorial possessions now owned or which may be hereafter acquired by the United States of America. Assignee will hold all rights for its own use and benefit and for the use and benefit of its successors or assigns to the full end of the term for which the LETTERS PATENT may be granted, as fully and entirely as the same would have been held and enjoyed by Assignors if this assignment and sale had not been made. Assignors request and authorize the Commissioner of the U.S. Patent and Trademark Office, and foreign counterpart officials of foreign patent offices, to issue respective LETTERS PATENT in the United States and foreign countries when granted, in accordance with this assignment.

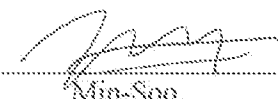
Assignors further covenant and agree with the Assignee that Assignors have a full and unencumbered title to the Assignors' interests in the Invention, which title Assignors warrant to the Assignee. Assignors further agree that Assignors will, without demanding any further consideration therefor, at the request and expense of the Assignee, do all lawful and just acts, including the execution and acknowledgment of instruments, that may be or become necessary for obtaining, sustaining, extending, reissuing or reexamining United States and foreign LETTERS PATENT or the like for the Invention, and for maintaining and perfecting the Assignee's right to the Invention and LETTERS PATENT, particularly in cases of interference conflict, opposition and litigation.

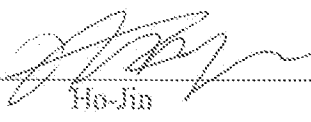
IN TESTIMONY WHEREOF, we have each signed this Assignment on the respective dates specified below.

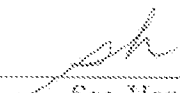
  
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Sung-Hoon Ahn  
Date 28 Feb 2019

  
\_\_\_\_\_  
Gil-Yong Lee  
Date 28 Feb 2019

  
\_\_\_\_\_  
Hyung-Soo Kim  
Date 28 Feb 2019

  
\_\_\_\_\_  
Min-Soo Kim  
Date 28 Feb 2019

  
\_\_\_\_\_  
Ho-Jin Kim  
Date 28 Feb 2019

  
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Soo-Hong Min  
Date 28 Feb 2019